



AUTOMATED CHEMICAL SOLUTIONS

Chemicals and Controllers for PWB Fabrication

Product Overview

I-Tin 8800

Immersion Tin Process

Product Description

The I-Tin 8800 immersion tin process is a cost effective, environmentally friendly tin plating process designed as an alternative final finish to hot air solder leveling. The I-Tin 8800 process provides a thick, level and solderable deposit of tin on copper and copper alloy substrates. The IT-8820 plating bath is uniquely formulated to inhibit copper-tin intermetallic growth so that the I-Tin 8800 surface will remain solderable for up to one year when stored under nominal conditions. The I-Tin 8800 process includes a unique post clean step, PC-8830, that greatly reduces surface ionic contamination and inhibits dendrite growth. The I-Tin 8800 process can also be used to restore solderability to oxidized or aged tin deposits that are exhibiting poor solderability.

FEATURES	BENEFITS
💡 Inhibited intermetallic growth	👉 Preserves solderability and increases shelf life
💡 Restores solderability of aged tin or solder deposits	👉 Minimizes reprocessing time

Physical Properties

	TI-8810	IT-8820	IT-8821
Specific gravity:	1.1	1.1	1.55
pH:	< 1	< 1	< 3
Odor:	Mild sulfide	Mild sulfide	Odorless
Appearance:	Clear, yellow liquid	Clear, yellow liquid	Clear, colorless liquid

Storage

Store in original containers above 40 °F. DO NOT FREEZE.

Safety

Avoid contact with eyes, skin and clothing. Wear chemical handler's gloves, goggles and protective clothing when handling. Read and understand Material Safety Data Sheet before using this product.

Notice

The information and recommendations of Automated Chemical Solutions, Inc., and its representatives, regarding this product are, to the best of our knowledge, true and accurate. We make no guarantee of results because the conditions of actual use are beyond our control. We assume no liability for damages or penalties resulting from the use of this product or following our recommendations. Our recommendations and suggestions for use of this product are not intended to grant license to operate under or infringe any patent.